

IN THE CLAIMS:

Claims 6-9, 16-19, 21-38 and 44-47 were previously canceled. Claims 13 and 14 have been amended herein. All of the pending claims 1 through 48 are presented below. This listing of claims will replace all prior versions and listings of claims in the application. Please enter these claims as amended.

Listing of Claims:

1. (Previously presented) A contact structure, comprising:
a substantially planar substrate;
at least one conductive compliant contact including:
a portion fixed within a portion of the substrate; and
at least one laterally unsupported portion integral with the portion fixed within the portion of the substrate, within a thickness of the substrate and extending beyond one side thereof; and
the substrate further configured to receive therein at least a portion of the at least one laterally unsupported portion when the at least one laterally unsupported portion flexs.
2. (Original) The contact structure of claim 1, wherein the at least one compliant contact has a generally rectangular cross-section perpendicular to a longitudinal extent thereof.

3. (Previously presented) A contact structure, comprising:
a substantially planar substrate; and
at least one conductive compliant contact including:
a portion fixed within a portion of the substrate; and
at least one laterally unsupported portion integral with the portion fixed within the portion
of the substrate, within a thickness of the substrate and extending beyond one side
thereof, wherein the substrate is further configured with a recess extending
peripherally about the at least one laterally unsupported portion of the at least one
compliant contact.

4. (Previously presented) A contact structure, comprising:
a substantially planar substrate; and
at least one conductive compliant contact including:
a portion fixed within a portion of the substrate;
at least one laterally unsupported portion integral with the portion fixed within the portion
of the substrate, within a thickness of the substrate and extending beyond one side
thereof; and
a conductive element operably coupled to the portion of the at least one compliant contact
fixed within the portion of the substrate and extending across a side thereof
opposite the one side beyond which the at least one laterally unsupported portion
extends.

5. (Original) The contact structure of claim 1, wherein the at least one laterally
unsupported portion of the at least one compliant contact is orthogonally compliant with respect
to a plane of the substrate.

6-9 (Canceled)

10. (Previously presented) A contact structure, comprising:
a substantially planar substrate; and
at least one conductive compliant contact including:
a portion fixed within a portion of the substrate;
at least one laterally unsupported portion integral with the portion fixed within the portion
of the substrate, within a thickness of the substrate and extending beyond one side
thereof; and
a dielectric layer laterally surrounding the portion of the at least one compliant contact
fixed within the portion of the substrate.

11. (Previously presented) A contactor card for use in testing a semiconductor
substrate, comprising:
a substantially planar substrate;
a plurality of conductive compliant contacts carried by the substrate and arranged in a pattern
selected for contact with contact pads carried by a semiconductor substrate to be tested,
each compliant contact of the plurality including:
a portion fixed within a portion of the planar substrate; and
at least one laterally unsupported portion integral with the portion fixed within the portion
of the substrate, within a thickness of the substrate and extending beyond one side
thereof; and
the substrate further configured to receive therein at least a portion of the at least one laterally
unsupported portion when the at least one laterally unsupported portion flexes.

12. (Original) The contactor card of claim 11, wherein the plurality of compliant
contacts each have a generally rectangular cross-section perpendicular to a longitudinal extent
thereof.

13. (Currently Amended) A contactor card for use in testing a semiconductor substrate, comprising:
a substantially planar substrate; and
a plurality of conductive compliant contacts carried by the planar substrate and arranged in a pattern selected for contact with contact pads carried by a semiconductor substrate to be tested, each compliant contact of the plurality including:
a portion fixed within a portion of the planar substrate;
at least one laterally unsupported portion integral with the portion fixed within the portion of the planar substrate, within a thickness of the planar substrate and extending beyond one side thereof; and
wherein the planar substrate is further configured with a recess extending peripherally about the at least one laterally unsupported portion of each of the plurality of compliant contacts.

14. (Currently Amended) A contactor card for use in testing a semiconductor substrate, comprising:
a substantially planar substrate; and
a plurality of conductive compliant contacts carried by the planar substrate and arranged in a pattern selected for contact with contact pads carried by a semiconductor substrate to be tested, each compliant contact of the plurality including:
a portion fixed within a portion of the planar substrate;
at least one laterally unsupported portion integral with the portion fixed within the portion of the substrate, within a thickness of the planar substrate and extending beyond one side thereof; and
a conductive element operably coupled to the portion of at least some of the plurality of compliant contacts fixed within the portion of the planar substrate and extending across a side thereof opposite the one side beyond which the at least one laterally unsupported portion extends.

15. (Previously Presented) The contactor card of claim 11, wherein the at least one laterally unsupported portion of each of the plurality of compliant contacts is orthogonally compliant with respect to a plane of the planar substrate.

16-19 (Canceled)

20. (Previously presented) A contactor card for use in testing a semiconductor substrate, comprising:
a substantially planar substrate; and
a plurality of conductive compliant contacts carried by the substrate and arranged in a pattern selected for contact with contact pads carried by a semiconductor substrate to be tested, each compliant contact of the plurality including:
a portion fixed within a portion of the planar substrate;
at least one laterally unsupported portion integral with the portion fixed within the portion of the substrate, within a thickness of the substrate and extending beyond one side thereof; and
a dielectric layer laterally surrounding the portion of each of the plurality of compliant contacts fixed within the portion of the planar substrate.

21-38 (Canceled)

39. (Previously presented) A semiconductor substrate testing system, comprising:
a contactor card configured for operable coupling with a semiconductor substrate to be tested,
including:
a substantially planar substrate; and
a plurality of conductive compliant contacts carried by the substrate of the contactor card
and arranged in a pattern selected for contact with contact pads carried by the
semiconductor substrate to be tested, each compliant contact of the plurality
including:
a portion fixed within a portion of the substrate of the contactor card; ~~and~~
at least one laterally unsupported portion integral with the portion fixed within the
portion of the substrate of the contactor card, within a thickness of the
substrate of the contactor card and extending beyond one side thereof; and
the substrate further configured to receive therein at least a portion of the at least
one laterally unsupported portion when one of the at least one laterally
unsupported portion flexes; and
a tester operably coupled to the contactor card and configured to apply test signals to the
semiconductor substrate through the contactor card.

40. (Original) The testing system of claim 39, wherein the plurality of compliant
contacts each have a generally rectangular cross-section perpendicular to a longitudinal extent
thereof.

41. (Previously presented) A semiconductor substrate testing system, comprising:
a contactor card configured for operable coupling with a semiconductor substrate to be tested,
including:
a substantially planar substrate; and
a plurality of conductive compliant contacts carried by the substrate of the contactor card
and arranged in a pattern selected for contact with contact pads carried by the
semiconductor substrate to be tested, each compliant contact of the plurality
including:
a portion fixed within a portion of the substrate of the contactor card; and
at least one laterally unsupported portion integral with the portion fixed within the
portion of the substrate of the contactor card, within a thickness of the
substrate of the contactor card and extending beyond one side thereof;
a tester operably coupled to the contactor card and configured to apply test signals to the
semiconductor substrate through the contactor card; and
wherein the substrate of the contactor card is further configured with a recess extending
peripherally about the at least one laterally unsupported portion of each of the plurality of
compliant contacts.

42. (Previously presented) A semiconductor substrate testing system, comprising:
a contactor card configured for operable coupling with a semiconductor substrate to be tested,
including:
a substantially planar substrate; and
a plurality of conductive compliant contacts carried by the substrate of the contactor card
and arranged in a pattern selected for contact with contact pads carried by the
semiconductor substrate to be tested, each compliant contact of the plurality
including:
a portion fixed within a portion of the substrate of the contactor card; and
at least one laterally unsupported portion integral with the portion fixed within the
portion of the substrate of the contactor card, within a thickness of the
substrate of the contactor card and extending beyond one side thereof;
a conductive element operably coupled to the portion of at least some of the
plurality of compliant contacts fixed within the portion of the substrate of
the contactor card and extending across a side thereof opposite the side
beyond which the at least one laterally unsupported portion extends; and
a tester operably coupled to the contactor card and configured to apply test signals to the
semiconductor substrate through the contactor card.

43. (Previously Presented) The testing system of claim 39, wherein the at least one
laterally unsupported portion of each of the compliant contacts of the plurality of compliant
contacts is orthogonally compliant with respect to a plane of the substrate of the contactor card.

44-47 (Canceled)

48. (Previously presented) A semiconductor substrate testing system, comprising:
a contactor card configured for operable coupling with a semiconductor substrate to be tested,
including:
a substantially planar substrate; and
a plurality of conductive compliant contacts carried by the substrate of the contactor card
and arranged in a pattern selected for contact with contact pads carried by the
semiconductor substrate to be tested, each compliant contact of the plurality
including:
a portion fixed within a portion of the substrate of the contactor card; and
at least one laterally unsupported portion integral with the portion fixed within the
portion of the substrate of the contactor card, within a thickness of the
substrate of the contactor card and extending beyond one side thereof;
a dielectric layer laterally surrounding the portion of each of the plurality of
compliant contacts fixed within the portion of the substrate of the
contactor card; and
a tester operably coupled to the contactor card and configured to apply test signals to the
semiconductor substrate through the contactor card.